

## Complementary Enhancement Mode MOSFET

### 1. Product Information

#### 1.1 Features

- Surface-mounted package
- Advanced trench cell design

#### 1.2 Applications

- MB and NB
- Motor drivers
- Half – bridge Drivers

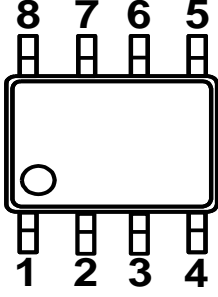
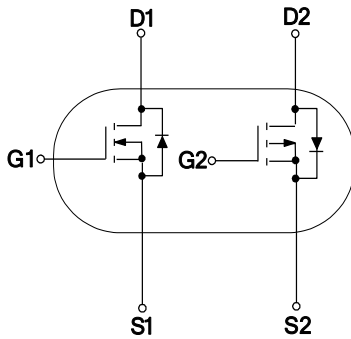
#### 1.3 Quick reference N-channel

- $BV \leq 60\text{ V}$
- $P_{tot} \leq 2\text{ W}$
- $I_D \leq 5.9\text{ A}$
- $R_{DS(ON)} \leq 35\text{ m}\Omega @ V_{GS} = 10\text{ V}$   
 $R_{DS(ON)} \leq 45\text{ m}\Omega @ V_{GS} = 4.5\text{ V}$

#### P-channel

- $BV \leq -60\text{ V}$
- $P_{tot} \leq 2\text{ W}$
- $I_D \leq -3.5\text{ A}$
- $R_{DS(ON)} \leq 95\text{ m}\Omega @ V_{GS} = -10\text{ V}$   
 $R_{DS(ON)} \leq 115\text{ m}\Omega @ V_{GS} = -4.5\text{ V}$

### 2. Pin Description

Pin	Description	Simplified Outline	Symbol
1	Source(S1)		
2	Gate(G1)		
3	Source(S2)		
4	Gate(G2)		
5,6	Drain(D2)		
7,8	Drain(D1)		

Top View  
SOP-8L



### 3. Limiting Values

Symbol	Parameter	Conditions	Min	Max	Unit
<b>N-channel</b>					
V <sub>DS</sub>	Drain-Source Voltage	T <sub>A</sub> = 25 °C	60	-	V
V <sub>GS</sub>	Gate-Source Voltage	T <sub>A</sub> = 25 °C	-	± 20	V
I <sub>D</sub> *	Drain Current	T <sub>A</sub> = 25 °C, V <sub>GS</sub> = -10 V	-	5.9	A
		T <sub>A</sub> = 100 °C, V <sub>GS</sub> = -10 V	-	3.7	A
I <sub>DM</sub> **	Pulsed Drain Current	T <sub>A</sub> = 25 °C, V <sub>GS</sub> = -10 V	-	23.6	A
<b>P-channel</b>					
V <sub>DS</sub>	Drain-Source Voltage	T <sub>A</sub> = 25 °C	- 60	-	V
V <sub>GS</sub>	Gate-Source Voltage	T <sub>A</sub> = 25 °C	-	± 20	V
I <sub>D</sub> *	Drain Current	T <sub>A</sub> = 25 °C, V <sub>GS</sub> = - 10 V	-	- 3.5	A
		T <sub>A</sub> = 100 °C, V <sub>GS</sub> = - 10 V	-	- 2.2	A
I <sub>DM</sub> **	Pulsed Drain Current	T <sub>A</sub> = 25 °C, V <sub>GS</sub> = - 10 V	-	- 14	A
P <sub>tot</sub>	Total Power Dissipation	T <sub>A</sub> = 25 °C	-	2	W
T <sub>stg</sub>	Storage Temperature		- 55	150	°C
T <sub>J</sub>	Junction Temperature		- 55	150	°C
R <sub>θJA</sub> *	Thermal Resistance- Junction to Ambient		-	62.5	°C / W

Notes :

- \* Surface Mounted on 1 in<sup>2</sup> pad area, t ≤ 10 sec
- \*\* Pulse width ≤ 10 μs, duty cycle ≤ 1 %

### 4. Marking Information

Product Name	Marking
KJ4717S	<div style="display: inline-block; background-color: black; color: white; padding: 2px;">4717 YWWXXX</div> YWWXXX: Date Code

### 5. Ordering Code

Product Name	Package	Reel Size	Tape width	Quantity	Note
KJ4717S	SOP8			3000	

Note: KUAJIJIXIN defines “ Green ” as lead-free ( RoHS compliant ) and halogen free ( Br or Cl does not exceed 900 ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500 ppm by weight; Follow IEC 61249-2-21 and IPC / JEDEC J-STD-020C )

**6. Electrical Characteristics** ( $T_A = 25\text{ }^\circ\text{C}$  Unless Otherwise Noted)

**N-channel:**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	60	-	-	V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{DS} = 250\text{ }\mu\text{A}$	1	-	2.5	V
$I_{DSS}$	Zero Gate Voltage Source Current	$V_{DS} = 48\text{ V}, V_{GS} = 0\text{ V}$	-	-	1	$\mu\text{A}$
		$T_J = 85\text{ }^\circ\text{C}$	-	-	30	$\mu\text{A}$
$I_{GSS}$	Gate Leakage Current	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$	-	-	$\pm 100$	nA
$R_{DS(on)}^a$	Drain-Source On-State Resistance	$V_{GS} = 10\text{ V}, I_D = 4\text{ A}$	-	30	35	m $\Omega$
		$V_{GS} = 4.5\text{ V}, I_D = 3\text{ A}$	-	36	45	
<b>Diode Characteristics</b>						
$V_{SD}^a$	Diode Forward Voltage	$I_{SD} = 4\text{ A}, V_{GS} = 0\text{ V}$	-	0.8	1.2	V
$t_{rr}$	Reverse Recovery Time	$I_{SD} = 4\text{ A}, di_{SD}/dt = 100\text{ A}/\mu\text{s}$	-	11	-	nS
$Q_{rr}$	Reverse Recovery Charge		-	7.5	-	nC
<b>Dynamic Characteristics<sup>b</sup></b>						
$C_{iss}$	Input Capacitance	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}$ Frequency = 1 MHz	-	1042	-	pF
$C_{oss}$	Output Capacitance		-	48.6	-	
$C_{rss}$	Reverse Transfer Capacitance		-	38	-	
$t_d(on)$	Turn-on Delay Time	$V_{DS} = 30\text{ V}, V_{GEN} = 10\text{ V},$ $R_G = 4.5\text{ }\Omega, R_L = 7.5\text{ }\Omega,$ $I_{DS} = 4\text{ A}$	-	4.6	-	nS
$t_r$	Turn-on Rise Time		-	19	-	
$t_d(off)$	Turn-off Delay Time		-	14	-	
$t_f$	Turn-off Fall Time		-	18	-	
<b>Gate Charge Characteristics<sup>b</sup></b>						
$Q_g$	Total Gate Charge	$V_{DS} = 30\text{ V}, V_{GS} = 10\text{ V},$ $I_{DS} = 4\text{ A}$	-	18.9	-	nC
$Q_{gs}$	Gate-Source Charge		-	4	-	
$Q_{gd}$	Gate-Drain Charge		-	2.5	-	

Notes :

 a : Pulse test ; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ 

b : Guaranteed by design, not subject to production testing

## 7. Electrical Characteristics (T<sub>A</sub>=25 °C Unless Otherwise Noted)

### P-channel:

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>DS</sub> = - 250 μA	- 60	-	-	V
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>DS</sub> = - 250 μA	- 1	-	- 2.5	V
I <sub>DSS</sub>	Drain Leakage Current	V <sub>DS</sub> = - 48 V, V <sub>GS</sub> = 0 V	-	-	- 1.0	μA
I <sub>GSS</sub>	Gate Leakage Current	V <sub>GS</sub> = 0 V, V <sub>GS</sub> = ± 20 V	-	-	±100	nA
R <sub>DS(ON)</sub> <sup>a</sup>	On-State Resistance	V <sub>GS</sub> = - 10 V, I <sub>DS</sub> = - 3 A	-	85	95	mΩ
		V <sub>GS</sub> = - 4.5 V, I <sub>DS</sub> = - 2 A	-	105	115	
Diode Characteristics						
V <sub>SD</sub> <sup>a</sup>	Diode Forward Voltage	I <sub>SD</sub> = - 3 A, V <sub>GS</sub> = 0 V	-	- 0.8	- 1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>SD</sub> = - 3 A, dI <sub>SD</sub> /dt = 100 A / μs	-	15.8	-	nS
Q <sub>rr</sub>	Reverse Recovery Charge		-	12.6	-	nC
Dynamic Characteristics <sup>b</sup>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = - 25 V Frequency = 1 MHz	-	889	-	pF
C <sub>oss</sub>	Output Capacitance		-	63	-	
C <sub>rss</sub>	Reverse Transfer Capacitance		-	52	-	
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> = - 30 V, V <sub>GEN</sub> = - 10 V, R <sub>G</sub> = 4.5 Ω, R <sub>L</sub> = 10 Ω, I <sub>DS</sub> = - 3 A	-	9	-	nS
t <sub>r</sub>	Turn-on Rise Time		-	25	-	
t <sub>d(off)</sub>	Turn-off Delay Time		-	107	-	
t <sub>f</sub>	Turn-off Fall Time		-	49	-	
Gate Charge Characteristics <sup>b</sup>						
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = - 10 V, I <sub>DS</sub> = - 3 A	-	16	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	4	-	
Q <sub>gd</sub>	Gate-Drain Charge		-	2.2	-	

Notes :

a : Pulse test ; pulse width ≤ 300 μs, duty cycle ≤ 2%

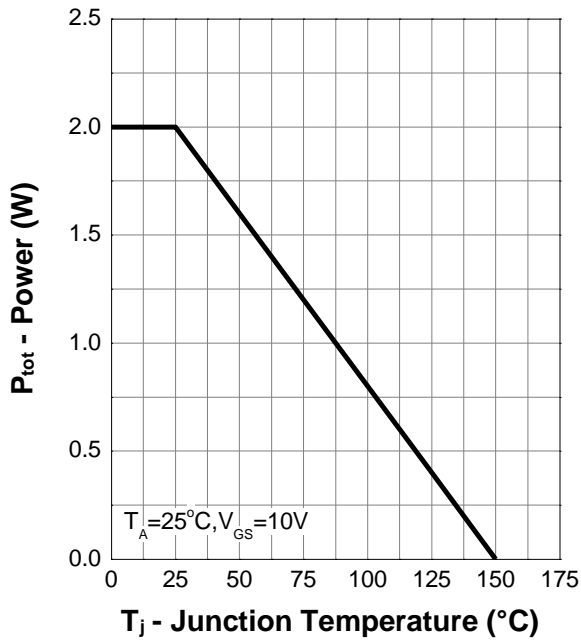
b : Guaranteed by design, not subject to production testing



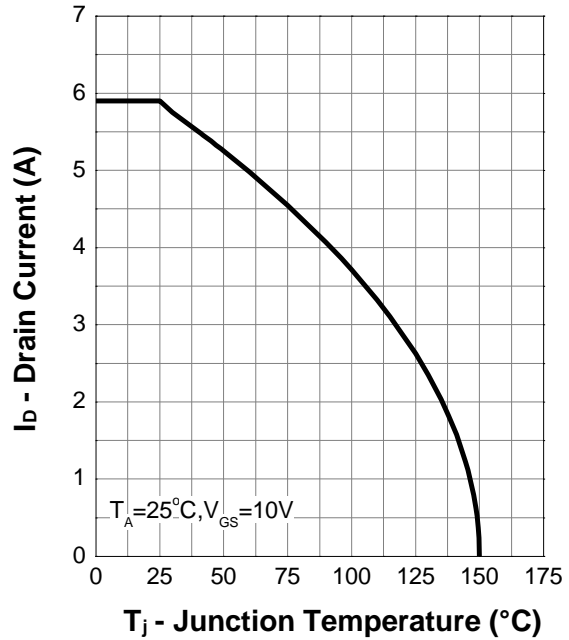
### 8. Typical Characteristics (Cont.)

N-channel:

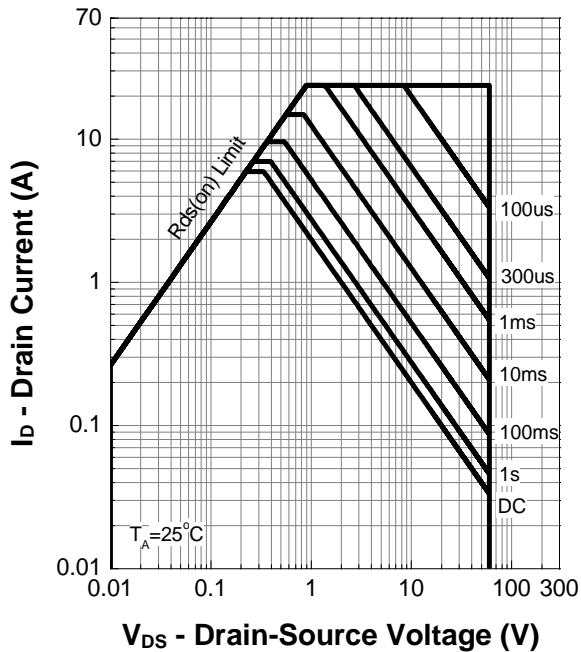
Power Capability



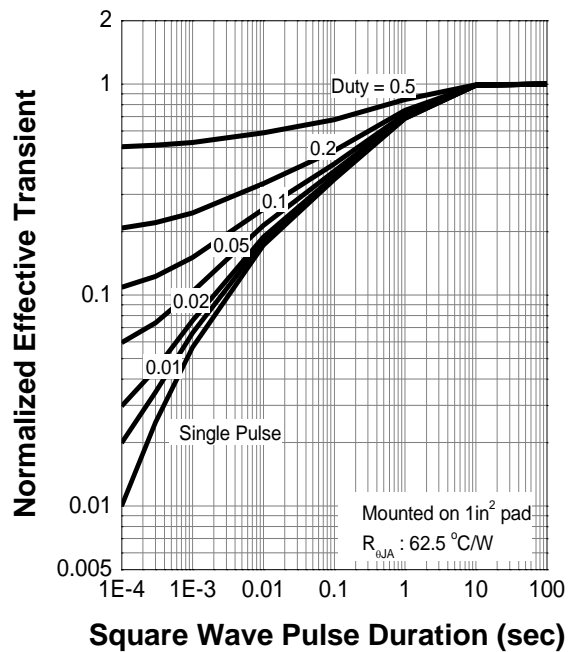
Current Capability



Safe Operatio. ea



Transient Thermal Impedance

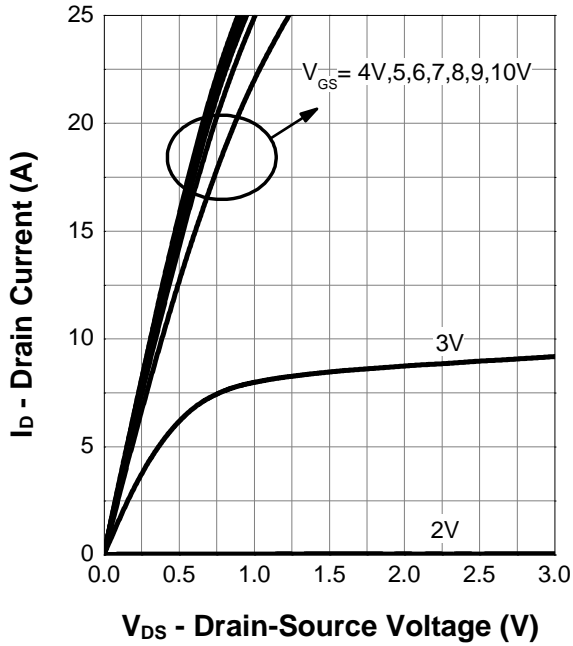




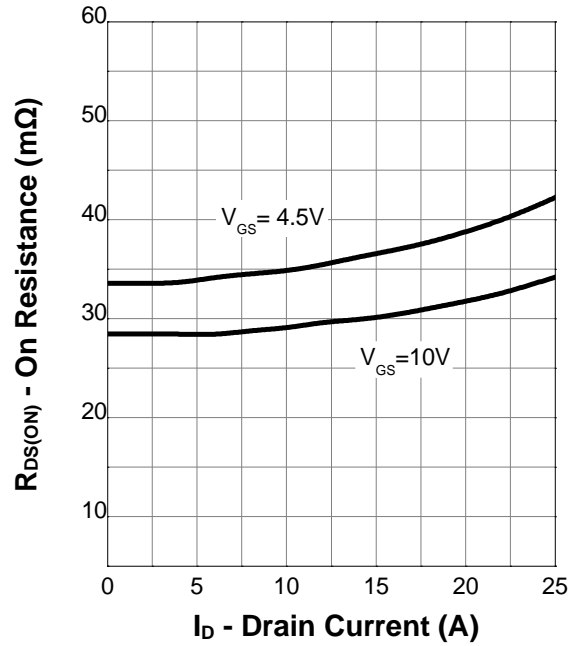
### 8. Typical Characteristics (Cont.)

N-channel:

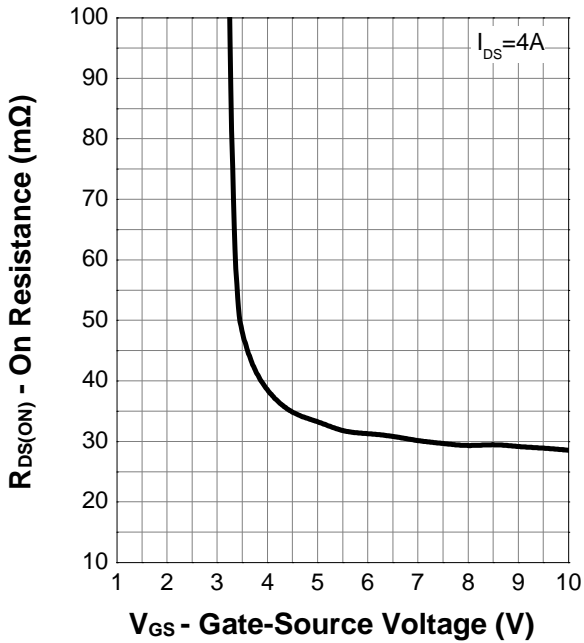
Output Characteristics



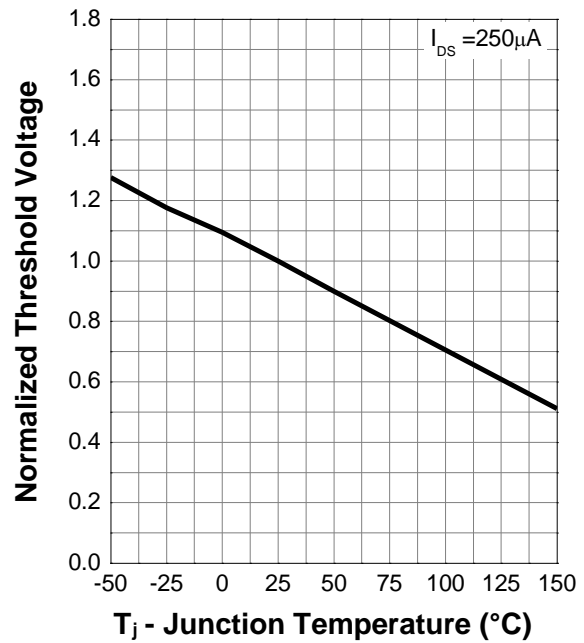
On Resistance



Transfer Characteristics



Normalized Threshold Voltage

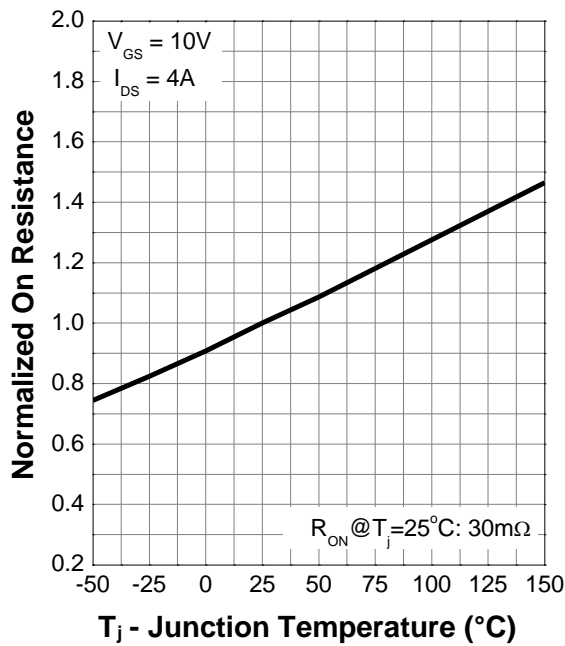




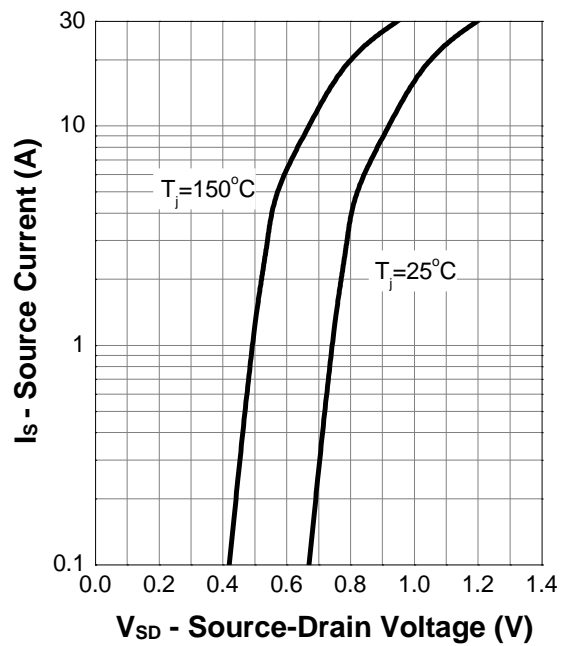
### 8. Typical Characteristics (Cont.)

N-channel:

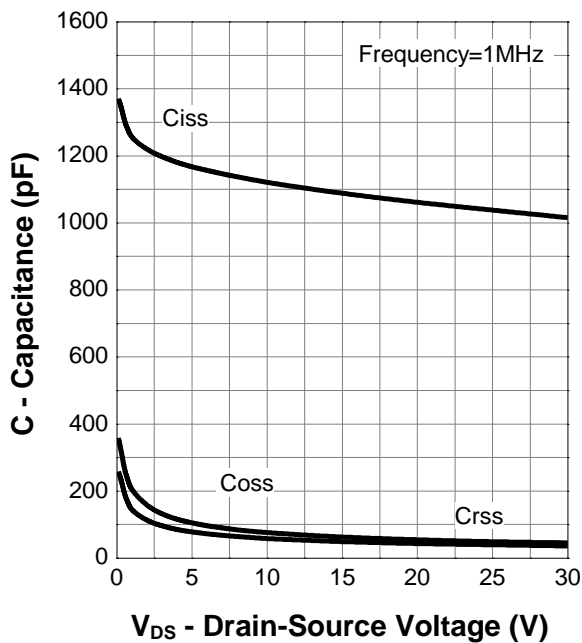
Normalized On Resistance



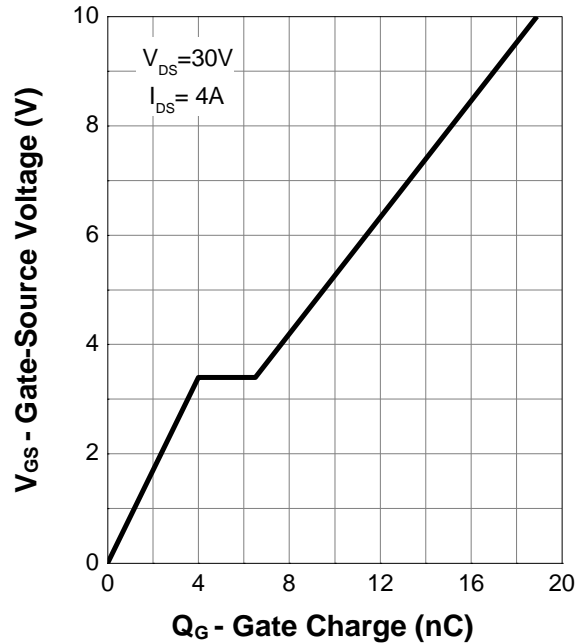
Diode Forward Current



Capacitance



Gate Charge

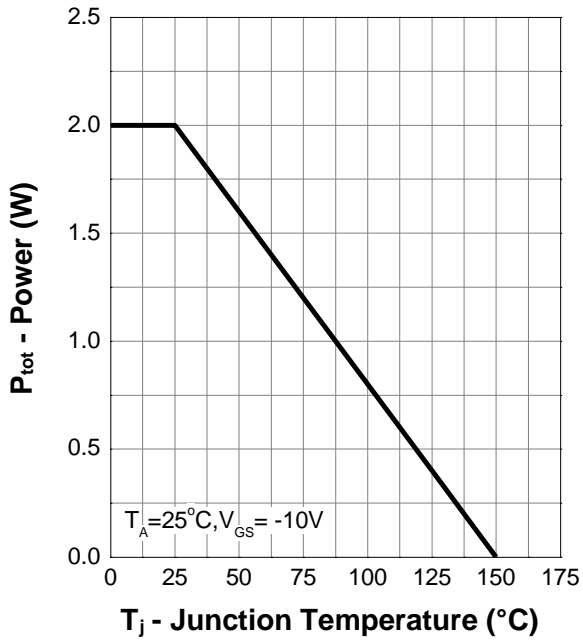




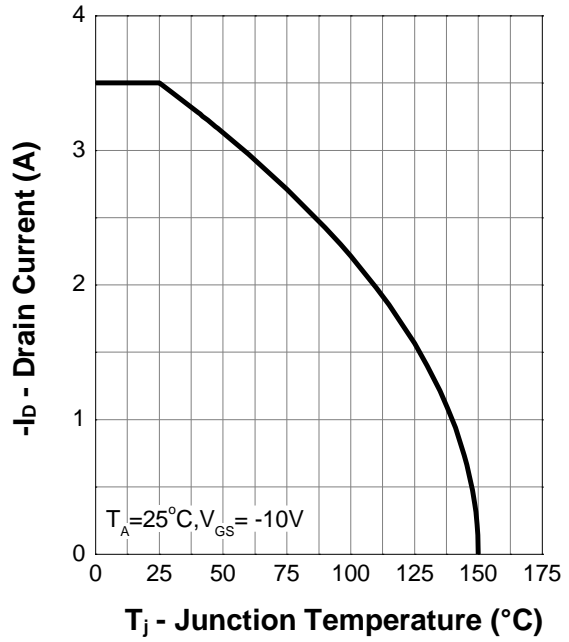
### 8. Typical Characteristics (Cont.)

P-channel:

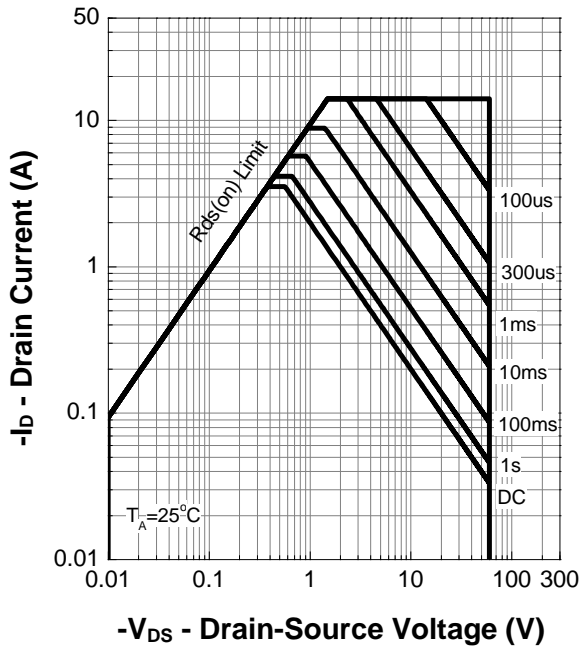
Power Capability



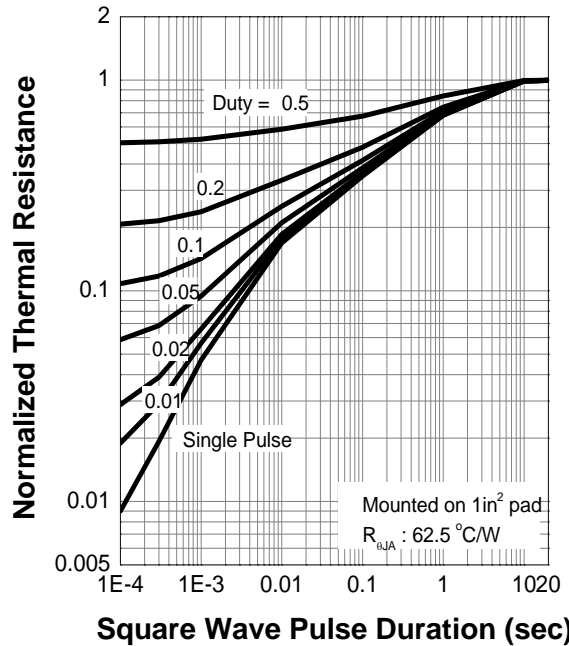
Current Capability



Safe Operation Area



Transient Thermal Impedance



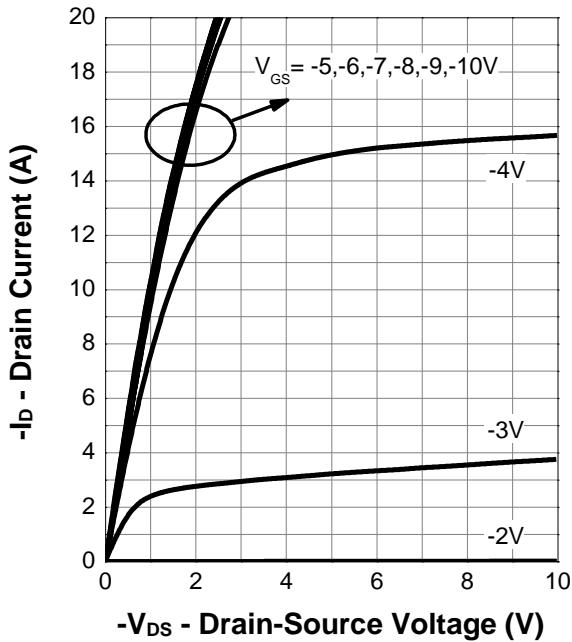




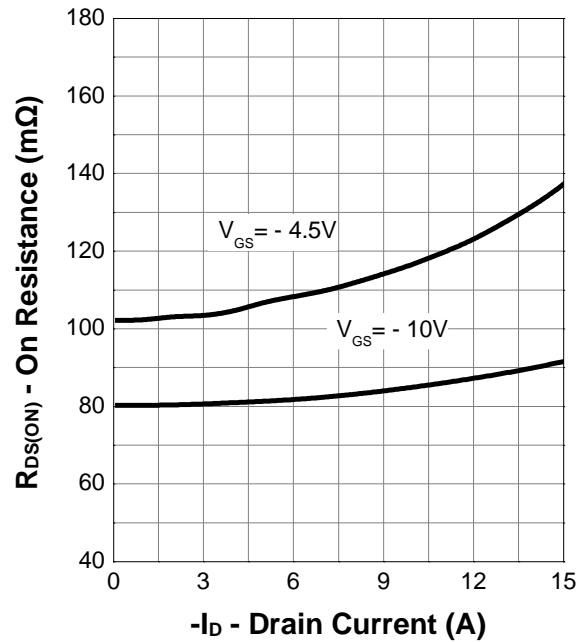
### 8. Typical Characteristics (Cont.)

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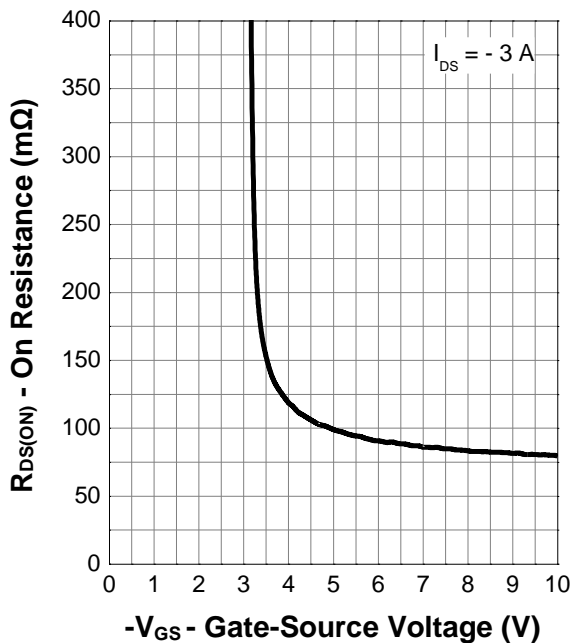
Output Characteristics



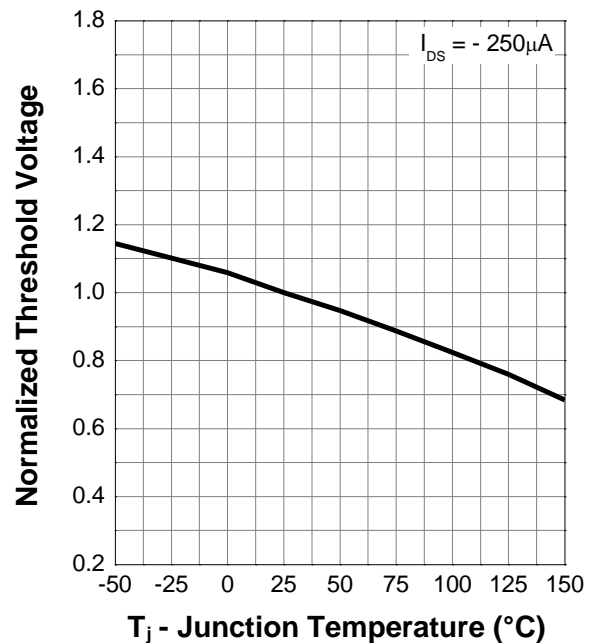
Drain-Source On Resistance



Transfer Characteristics



Normalized Threshold Voltage

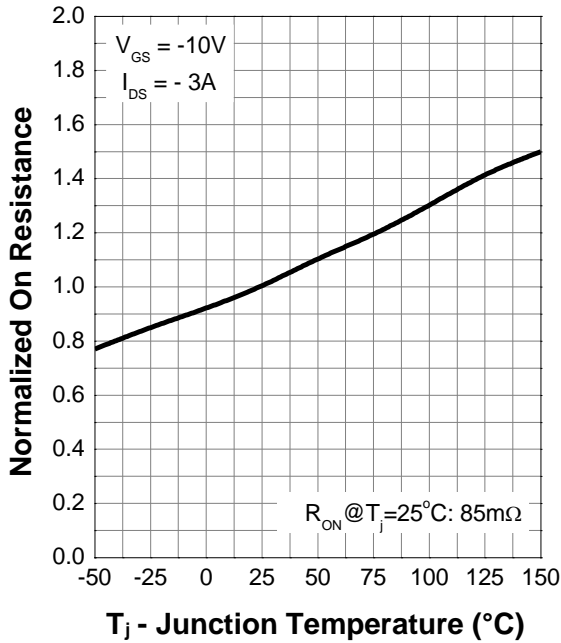




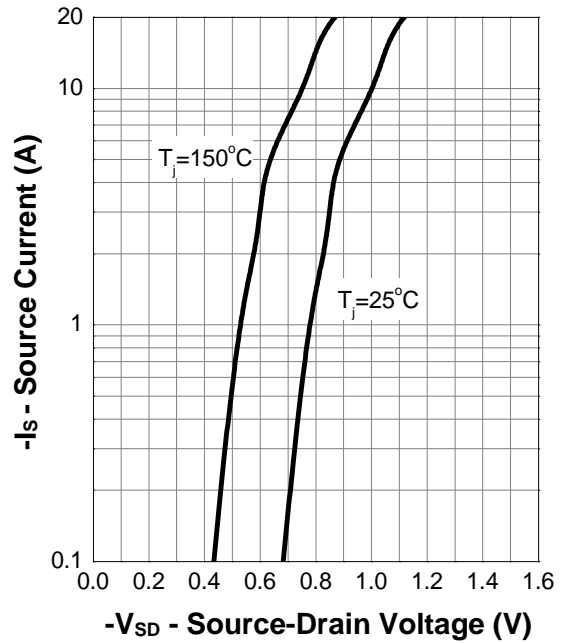
### 8. Typical Characteristics (Cont.)

P-channel:

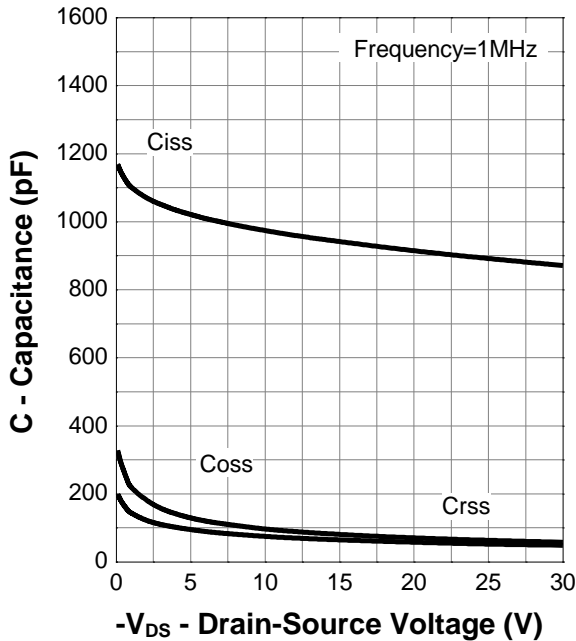
Normalized On Resistance



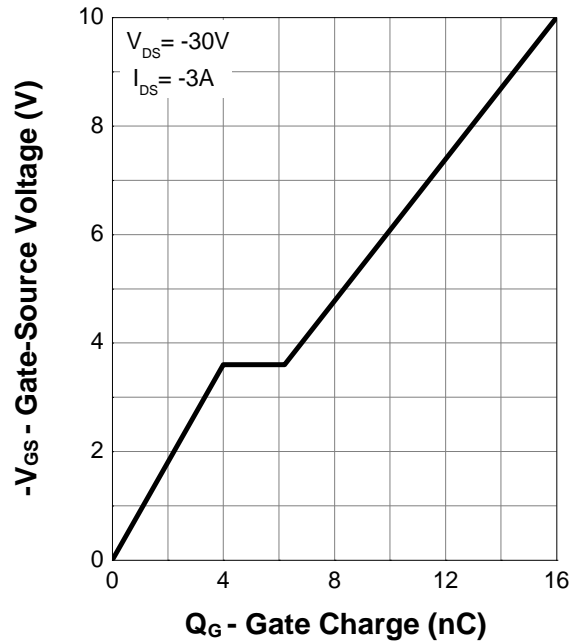
Diode Forward Current



Capacitance



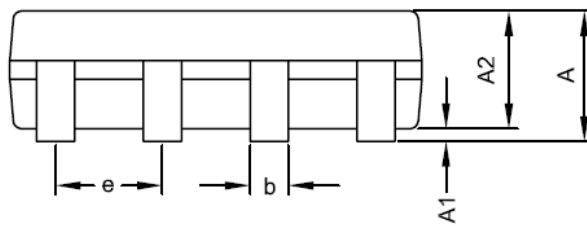
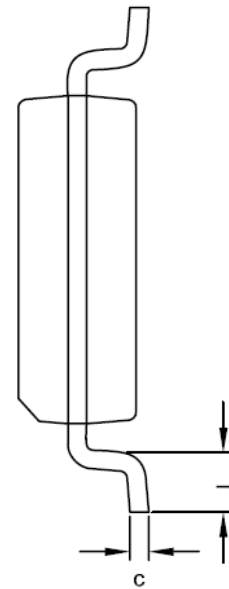
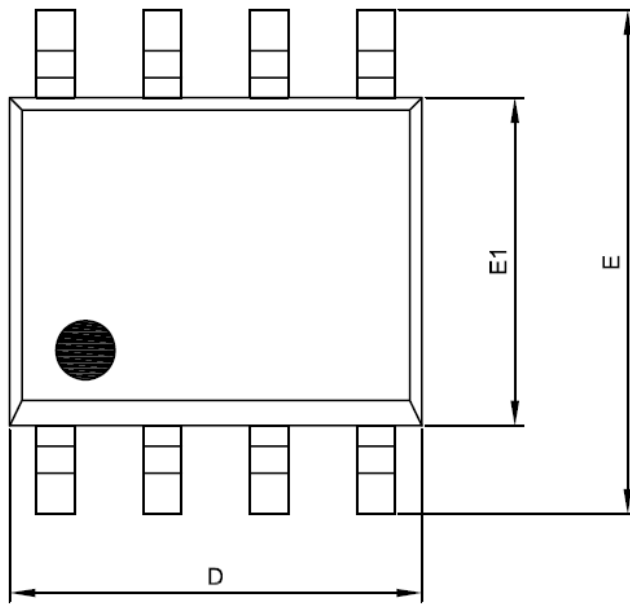
Gate Charge





## 9. Package Dimensions

SOP- 8L



Symbol	Dimensions In Millimeters	
	MIN.	MAX.
A	1.35	1.75
A1	0.00	0.25
A2	1.15	1.50
D	4.80	5.00
E	5.80	6.20
E1	3.80	4.00
c	0.19	0.27
b	0.33	0.53
e	1.27 BSC	
L	0.40	1.27

Notes :

1. Jedec outline : MS-012AA
2. Dimensions " D " does not include mold flash, protrusions and gate burrs shall not exceed .15 mm (.006 in) per side .
3. Dimensions " E1 " does not include inter-lead flash, or protrusions. Inter-lead flash and protrusions shall not exceed .25 mm (.010 in) per side.